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Chen et al.(10) **Pub. No.: US 2023/0230928 A1**(43) **Pub. Date: Jul. 20, 2023**(54) **SUBSTRATE, PACKAGED STRUCTURE, AND ELECTRONIC DEVICE**(71) Applicant: **HUAWEI TECHNOLOGIES CO., LTD.**, Guangdong (CN)(72) Inventors: **Huibin Chen**, Shanghai (CN); **Yongzhao Lin**, Dongguan (CN); **Zhen Lv**, Shanghai (CN)(73) Assignee: **HUAWEI TECHNOLOGIES CO., LTD.**, Guangdong (CN)(21) Appl. No.: **18/189,622**(22) Filed: **Mar. 24, 2023****Related U.S. Application Data**

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CPC **H01L 23/5386** (2013.01); **H01L 23/5383** (2013.01); **H01L 24/48** (2013.01); **H01L 2224/48157** (2013.01)(57) **ABSTRACT**

A substrate, a packaged structure, and an electronic device are provided. The substrate is configured to be electrically connected to a chip. The chip includes a power terminal and a signal terminal. The substrate includes a first substrate and a second substrate mounted on the first substrate. The first substrate includes a first layout, and the first layout is configured to be electrically connected to the power terminal. The second substrate includes a second layout, and the second layout is configured to be electrically connected to the signal terminal. A spacing between lines of the second layout is less than a spacing between lines of the first layout. The substrate provided in this application has a small size and high integration.

